



Description

JMT N And P-Channel Enhancement Mode MOSFET

Features

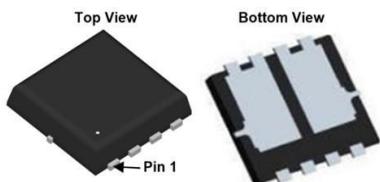
- N-Channel: 30V, 6A
 $R_{DS(ON)} < 36m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)} < 56m\Omega$ @ $V_{GS} = 4.5V$
- P-Channel: -30V, -5A
 $R_{DS(ON)} < 50m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)} < 78m\Omega$ @ $V_{GS} = -4.5V$
- Excellent Gate Charge x $R_{DS(ON)}$ Product(FOM)
- Very Low On-resistance $R_{DS(ON)}$
- Fast Switching Speed

Application

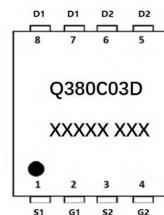
- Battery Protection
- Load Switch
- Power Management



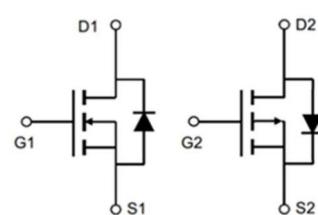
100% UIS TESTED!
100% ΔV_{ds} TESTED!



PDFN3x3-8L-D



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
Q380C03D	JMTQ380C03D	TAPING	PDFN3x3-8L-D	13inch	5000	50000

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max. N-Channel	Max. P-Channel	Units
V_{DSS}	Drain-Source Voltage		30	-30	V
V_{GSS}	Gate-Source Voltage		± 20	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	6	-5	A
		$T_C = 100^\circ C$	3.9	-3.3	A
I_{DM}	Pulsed Drain Current ^{note1}		24	-20	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		5.1	11	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	2.2	2.1	W
R_{eJC}	Thermal Resistance, Junction to Ambient		57	60	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150		°C

**N-Channel Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=3\text{A}$	-	28	36	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=2\text{A}$	-	40	56	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	233	-	pF
C_{oss}	Output Capacitance		-	44	-	pF
C_{rss}	Reverse Transfer Capacitance		-	33	-	pF
Q_g	Total Gate Charge	$V_{DS}=15\text{V}$, $I_D=2\text{A}$, $V_{GS}=10\text{V}$	-	3	-	nC
Q_{gs}	Gate-Source Charge		-	0.5	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	0.8	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}$, $I_D=4\text{A}$, $V_{GS}=10\text{V}$, $R_{REN}=3\Omega$	-	4	-	ns
t_r	Turn-on Rise Time		-	2.1	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	15	-	ns
t_f	Turn-off Fall Time		-	3.2	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	6	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	24	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=6\text{A}$	-	0.8	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{DD}=15\text{V}$, $V_G=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$, $I_{AS}=4.5\text{A}$
 $T_J=25^\circ\text{C}$, $V_{DD}=-15\text{V}$, $V_G=-10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$, $I_{AS}=-6.5\text{A}$
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

**P-Channel Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D= -250\mu\text{A}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}= -30\text{V}$, $V_{GS}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}= \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D= -250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}= -10\text{V}$, $I_D= -4.1\text{A}$	-	38	50	$\text{m}\Omega$
		$V_{GS}= -4.5\text{V}$, $I_D= -3.5\text{A}$	-	56	78	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}= -15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	580	-	pF
C_{oss}	Output Capacitance		-	98	-	pF
C_{rss}	Reverse Transfer Capacitance		-	74	-	pF
Q_g	Total Gate Charge	$V_{DS}= -15\text{V}$, $I_D= -4.1\text{A}$, $V_{GS}= -10\text{V}$	-	6.8	-	nC
Q_{gs}	Gate-Source Charge		-	1	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1.4	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}= -15\text{V}$, $I_D= -1\text{A}$, $V_{GS}= -10\text{V}$, $R_{\text{GEN}}=2.5\Omega$	-	14	-	ns
t_r	Turn-on Rise Time		-	61	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	19	-	ns
t_f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-5	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-20	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s= -5\text{A}$	-	-0.8	-1.2	V

Typical Performance Characteristics-N

Figure 1: Output Characteristics

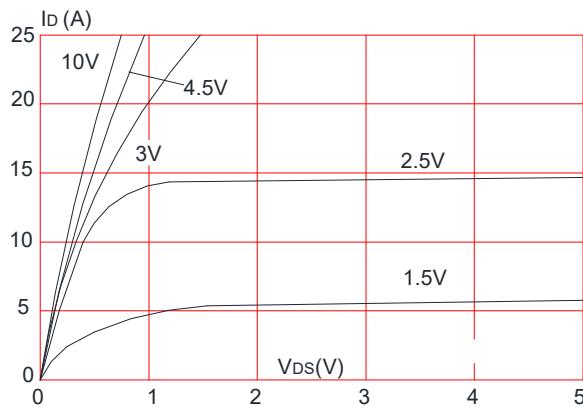


Figure 3: On-resistance vs. Drain Current

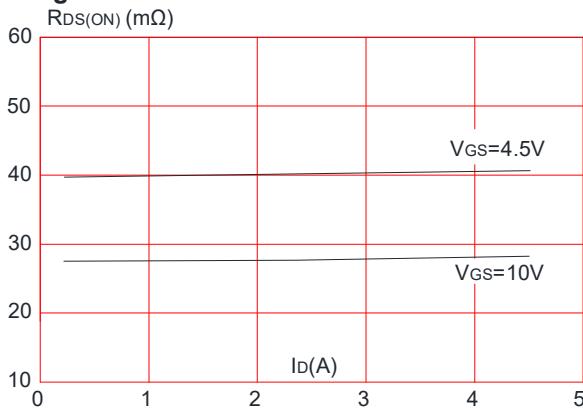


Figure 5: Gate Charge Characteristics

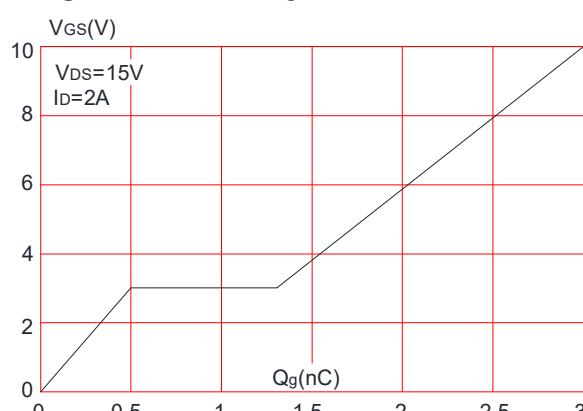


Figure 2: Typical Transfer Characteristics

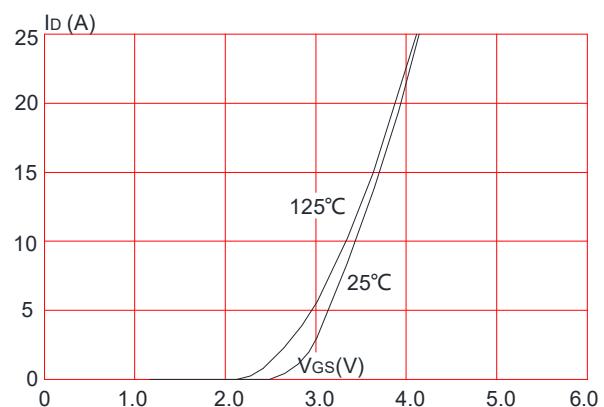


Figure 4: Body Diode Characteristics

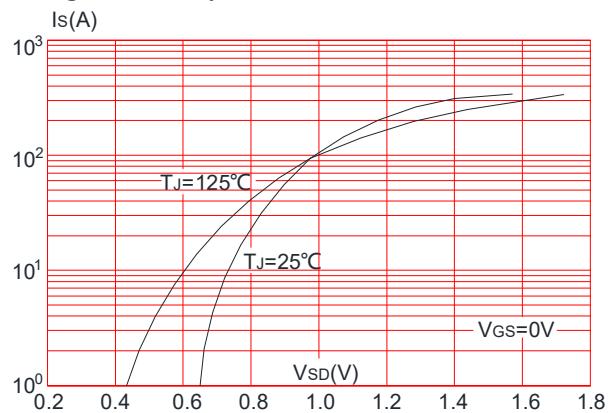


Figure 6: Capacitance Characteristics

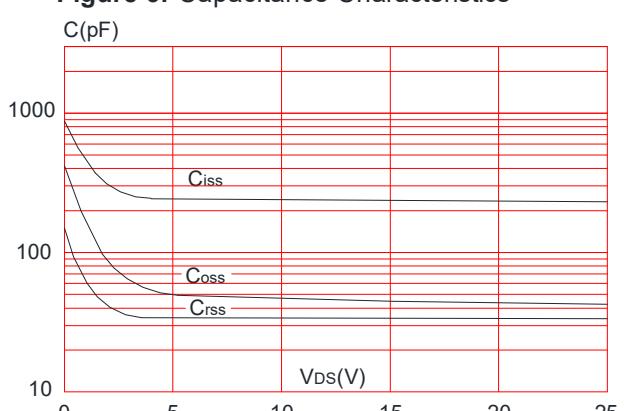


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

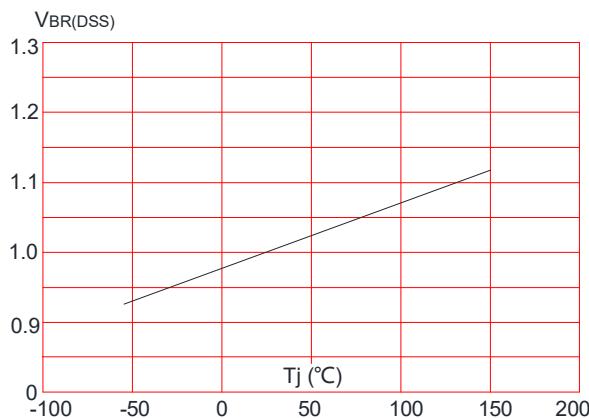


Figure 8: Normalized on Resistance vs. Junction Temperature

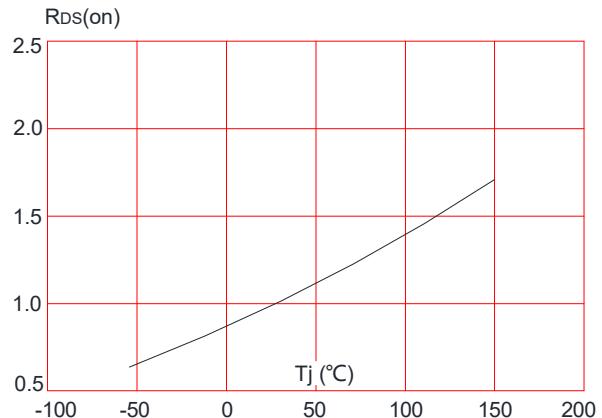


Figure 9: Maximum Safe Operating Area

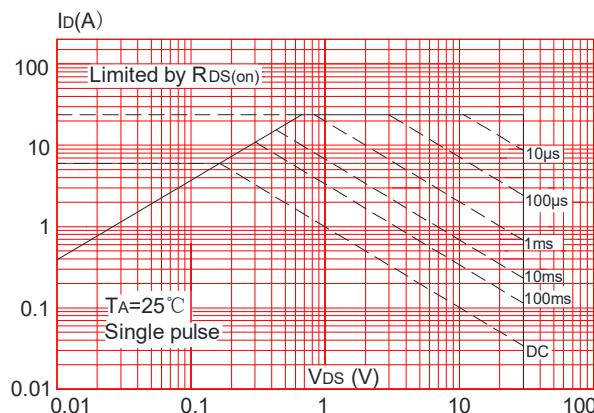


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

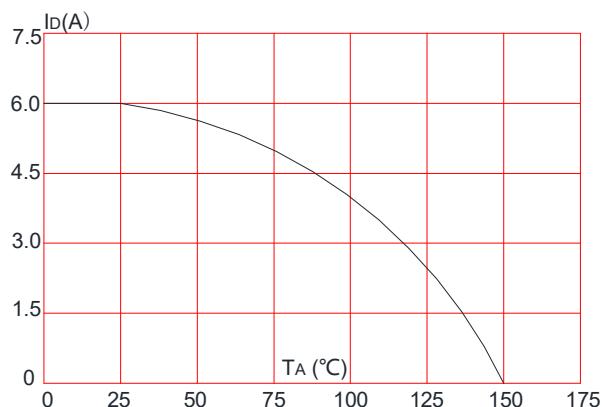
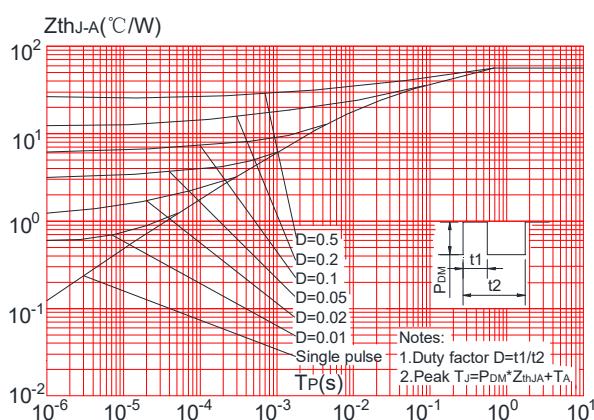


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Test Circuit-N

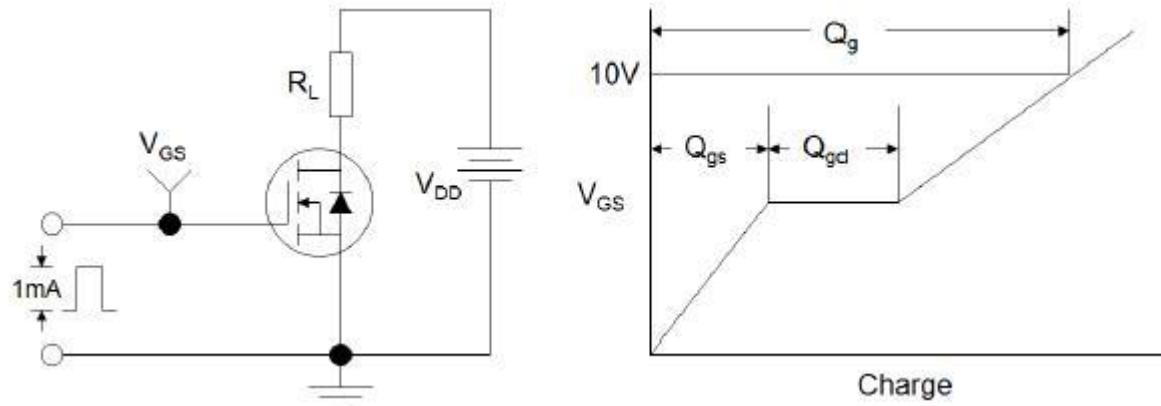


Figure1:Gate Charge Test Circuit & Waveform

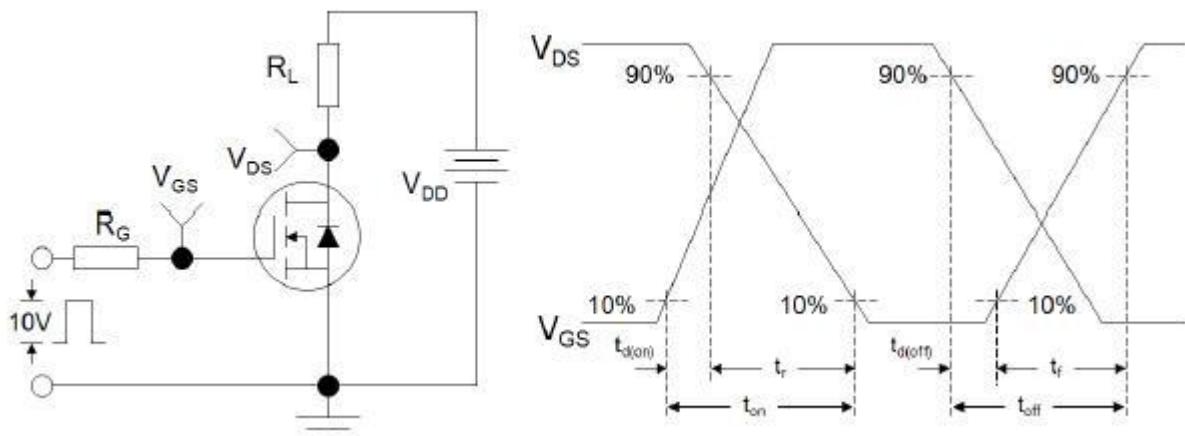


Figure 2: Resistive Switching Test Circuit & Waveforms

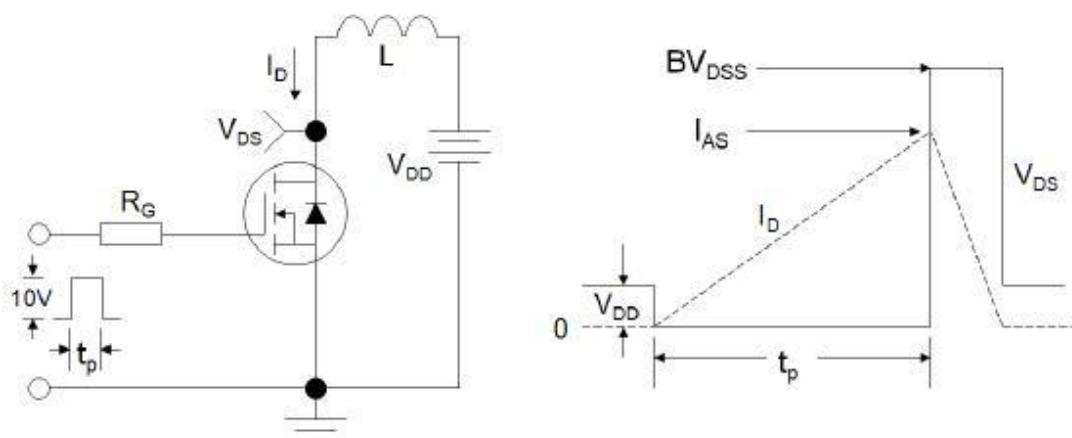


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Typical Performance Characteristics-P

Figure 1: Output Characteristics

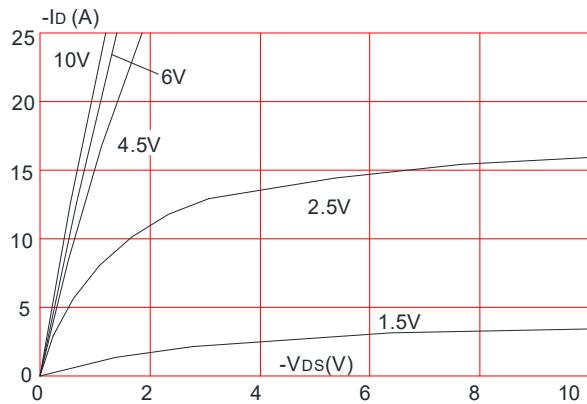


Figure 3: On-resistance vs. Drain Current

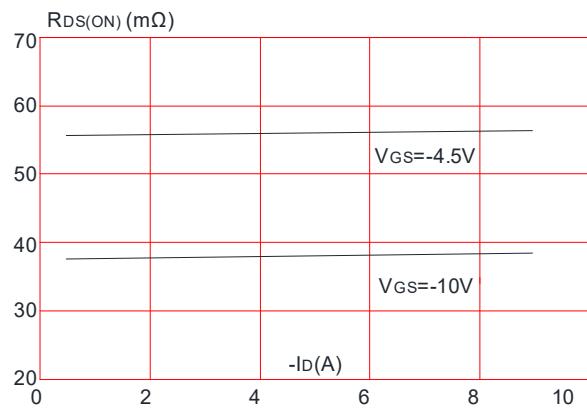


Figure 5: Gate Charge Characteristics

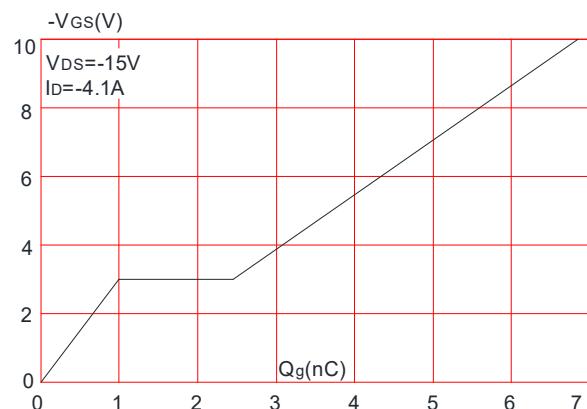


Figure 2: Typical Transfer Characteristics

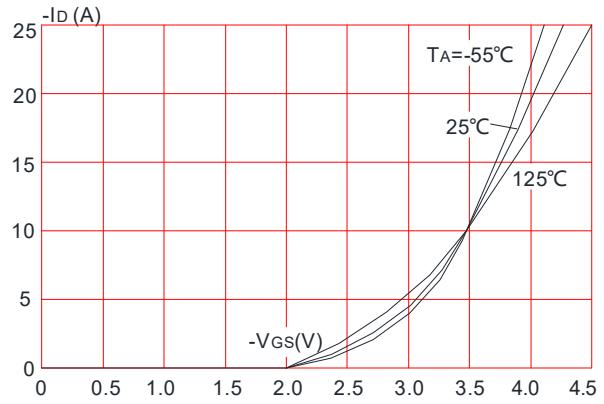


Figure 4: Body Diode Characteristics

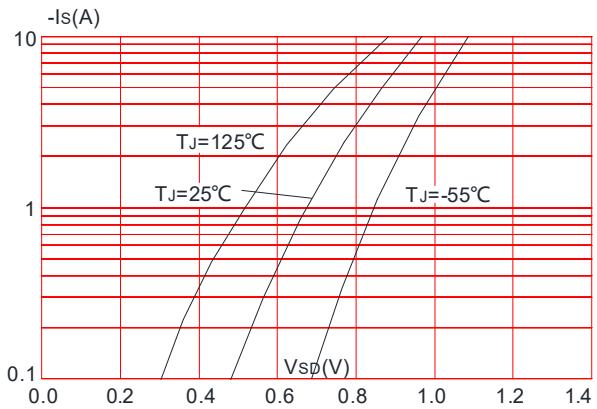


Figure 6: Capacitance Characteristics

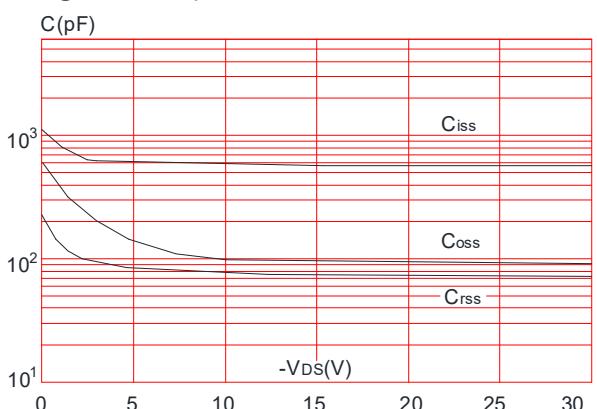


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

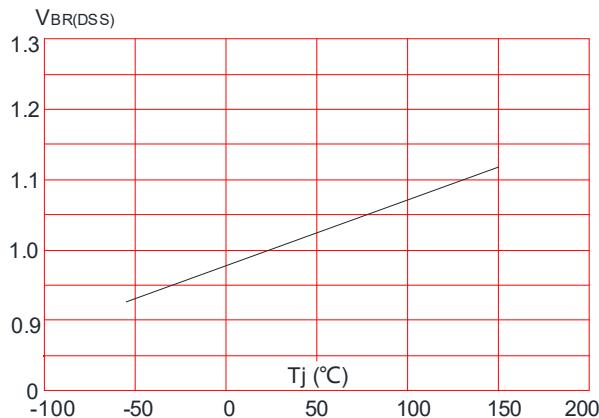


Figure 9: Maximum Safe Operating Area

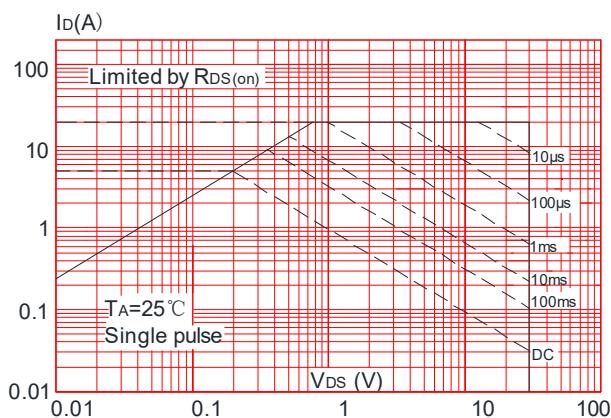


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

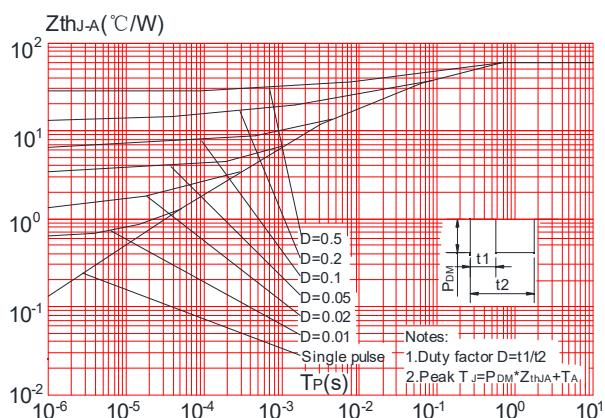


Figure 8: Normalized on Resistance vs. Junction Temperature

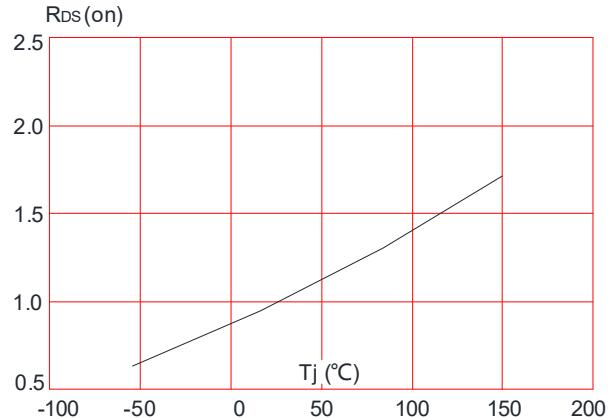
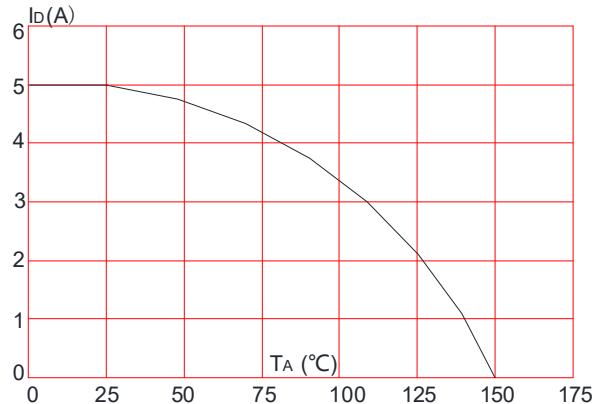
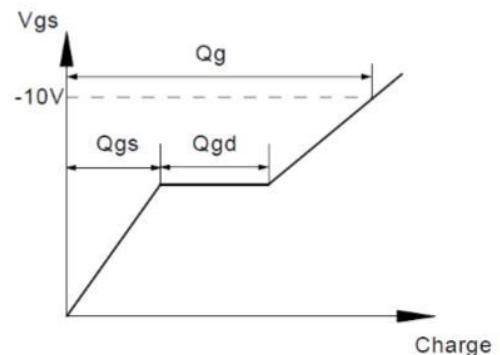
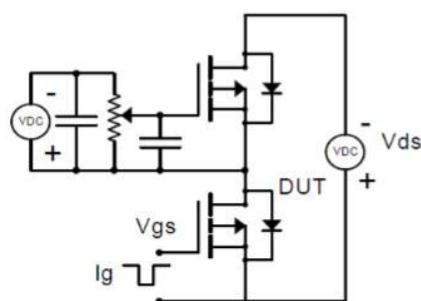


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

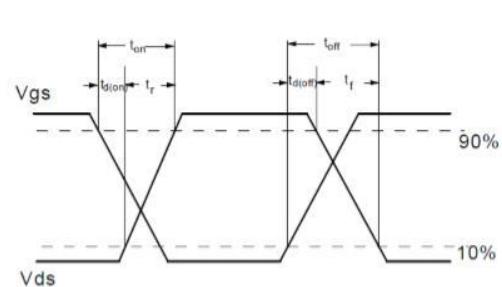
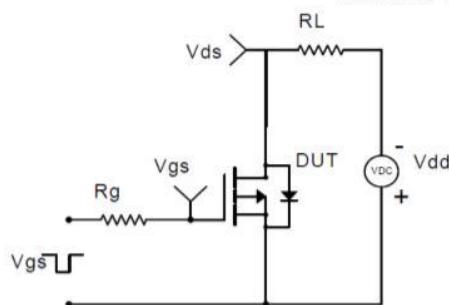


Test Circuit-P

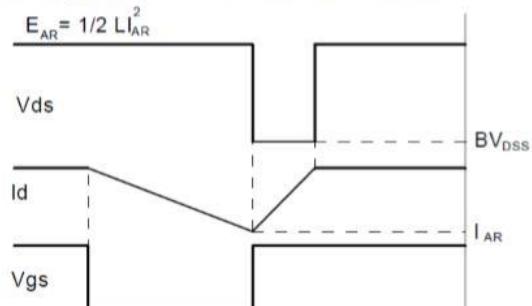
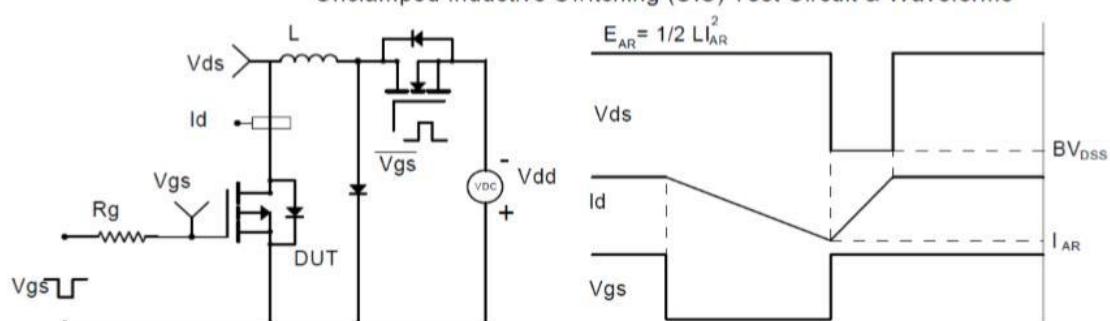
Gate Charge Test Circuit & Waveform



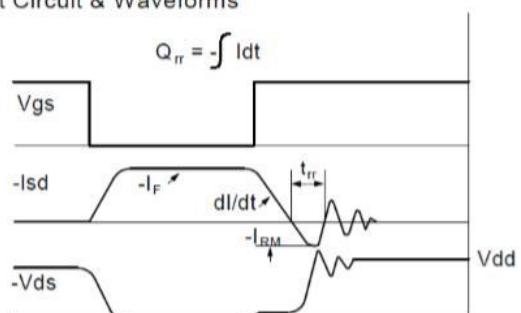
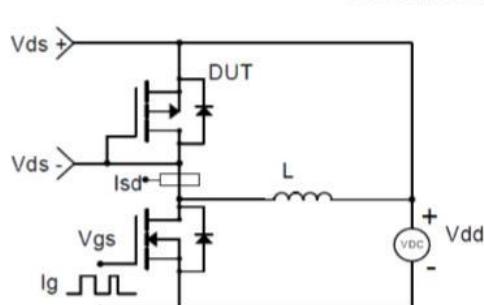
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

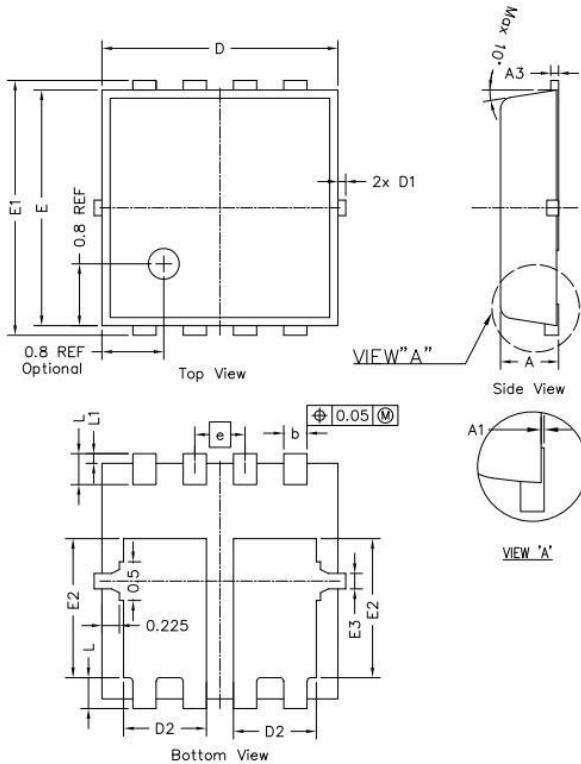


Diode Recovery Test Circuit & Waveforms





Package Mechanical Data-PDFN3x3-8L-D



SYMBOLS	DIMENSION IN MM			DIMENSION IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.700	0.750	0.800	0.028	0.030	0.031
A1	---	---	0.050	----	----	0.002
A3	0.144	0.152	0.202	0.006	0.006	0.008
b	0.250	0.300	0.350	0.010	0.012	0.014
e	0.65 BSC			0.026 BSC		
D	2.950	3.050	3.150	0.116	0.120	0.124
E	2.950	3.050	3.150	0.116	0.120	0.124
D1	---	---	0.125	----	----	0.005
E1	3.200	3.300	3.400	0.126	0.130	0.134
D2	0.970	1.070	1.170	0.038	0.042	0.046
E2	1.700	1.800	1.900	0.067	0.071	0.075
E3	0.150	0.200	0.250	0.006	0.008	0.010
L	0.300	0.400	0.500	0.012	0.016	0.020
L1	0.075	0.125	0.175	0.003	0.005	0.007

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